

40V Dual N-Channel Enhancement Mode MOSFET

Description

The PECN4890D6 uses advanced trench technology to provide excellent $R_{DS(ON)}$ with low gate charge.

This device is suitable for high side switch in SMPS and general purpose applications.

General Features

- ◆ $V_{DS} = 40V, ID = 35A$
 $R_{DS(ON)} = 6.3m\Omega$ (typical) @ $VGS = 10V$
 $R_{DS(ON)} = 8.5m\Omega$ (typical) @ $VGS = 4.5V$
- ◆ Excellent gate charge $\times R_{DS(ON)}$ product(FOM)
- ◆ Very low on-resistance $R_{DS(ON)}$
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating
- ◆ 100% UIS tested

Application

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification

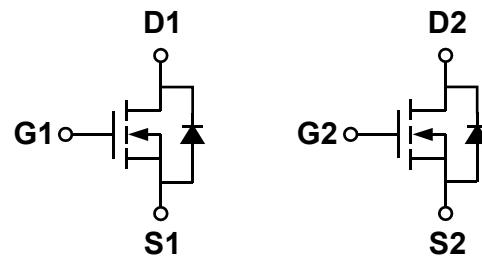
Package

100% UIS TESTED!

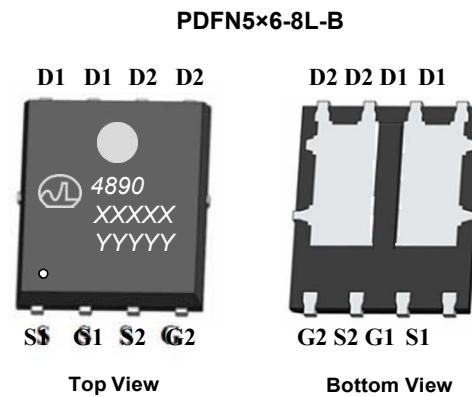
100% ΔVds TESTED!

- ◆ PDFN5*6-8L-B

Schematic diagram



Marking and pin assignment



Note:

XXXX is the date code.

YYYY is the Quality Code



Ordering Information

| Part Number | Storage Temperature | Package | Devices Per Reel |
|--------------|---------------------|--------------|------------------|
| PECN4890D6-G | -55°C to +150°C | PDFN5*6-8L-B | 5000 |

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

| parameter | symbol | limit | unit |
|--|----------|----------|------|
| Drain-source voltage | V_{DS} | 40 | V |
| Gate-source voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous (Silicon Limited) | I_D | 35 | A |
| | | 28 | |
| Pulsed Drain Current (Package Limited) | I_{DM} | 140 | A |
| Single pulse avalanche energy (L=0.1mH) | E_{AS} | 80 | mJ |
| Maximum power dissipation | P_D | 31 | W |
| | | 16 | |

| | | | |
|--------------------------------------|----------------|---------|----|
| Operating junction Temperature range | T _j | -55—150 | °C |
|--------------------------------------|----------------|---------|----|

Electrical Characteristics (TA=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|---------------------|---|-----|------|------|------|
| Static Characteristics | | | | | | |
| Drain-source breakdown voltage | BV _{DSS} | V _{GS} =0V, I _D =250μA | 40 | - | - | V |
| Zero gate voltage drain current | I _{DSS} | V _{DS} =40V, V _{GS} =0V | - | - | 1 | μA |
| | | T _J =85°C | - | - | 5 | |
| Gate Leakage Current | I _{GSS} | V _{DS} =0V, V _{GS} =±20V | - | - | ±100 | nA |
| Gate threshold voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =250μA | 1 | 1.5 | 2.3 | V |
| Drain-source on-state resistance ¹ | R _{DS(ON)} | V _{GS} =10V, I _D =25A | - | 6.3 | 7.5 | mΩ |
| | | V _{GS} =4.5V, I _D =15A | | 8.5 | 10 | |
| Forward Transconductance | g _{FS} | V _{DS} = 5V, I _D = 12A | | 60 | | S |
| Diode Characteristics | | | | | | |
| Diode Forward Voltage | V _{SD} | I _{SD} =1A, V _{GS} =0V | - | 0.82 | 1.1 | V |
| Diode Continuous Forward Current | I _S | | - | - | 2.5 | A |
| Reverse Recovery Time | t _{rr} | I _F =12A, dI/dt=100A/μs | - | 30 | - | ns |
| Reverse Recovery Charge | Q _{rr} | | - | 19 | - | nC |
| Dynamic Characteristics | | | | | | |
| Gate Resistance | R _G | V _{GS} =0V, V _{DS} =0V,f=1MHz | - | 3.5 | - | Ω |
| IEC/Nut capacitance | C _{ISS} | V _{GS} =0V ,V _{DS} =20V f=1.0MHz | - | 1500 | - | pF |
| Output capacitance | C _{OSS} | | - | 215 | - | |
| Reverse transfer capacitance | C _{rss} | | - | 135 | - | |
| Turn-on delay time | t _{D(ON)} | V _{GS} =10V, V _{DS} =20V, R _L =2Ω, R _G =3Ω | - | 6.4 | - | ns |
| Turn-on Rise time | t _r | | - | 17.2 | - | |
| Turn-off delay time | t _{D(OFF)} | | - | 29.6 | - | |
| Turn-off Fall time | t _f | | - | 16.8 | - | |
| Total gate charge | Q _g | V _{GS} =10V, V _{DS} =20V,I _D =12A | - | 27.2 | - | nC |
| Gate-source charge | Q _{gs} | | | 4.5 | | |
| Gate-drain charge | Q _{gd} | | - | 6.4 | - | |

Thermal Characteristics

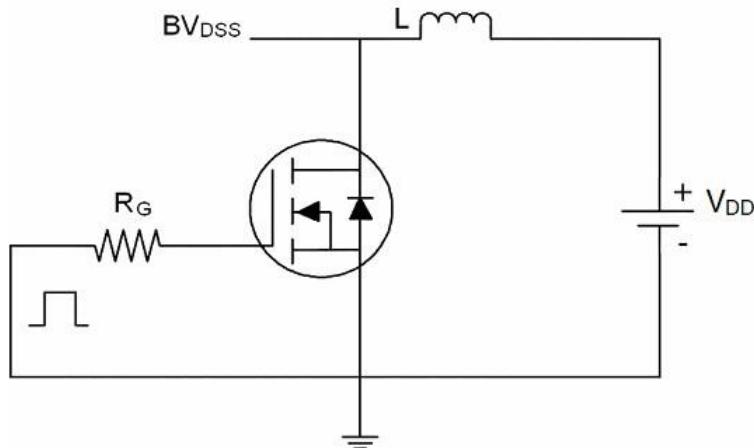
| Parameter | | Symbol | Typ | Max | Unit |
|--|--------------|------------------|-----|-----|------|
| Maximum Junction-to-Ambient ^A | ≤ 10s | R _{θJA} | 12 | 20 | °C/W |
| Maximum Junction-to-Ambient ^A | Steady-State | | 33 | 50 | |
| Maximum Junction-to-Lead ^B | Steady-State | | 2.4 | 2.9 | |

A:The value of R_{θJA} is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

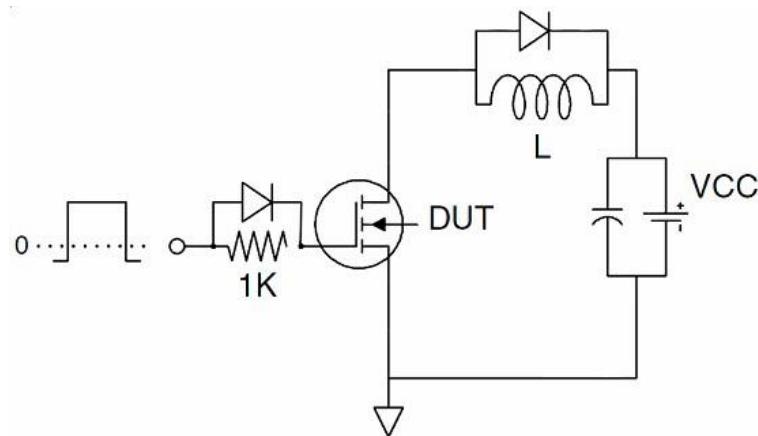
B: The R_{qJA} is the sum of the thermal impedance from junction to lead R_{qJL} and lead to ambient.

Test Circuit:

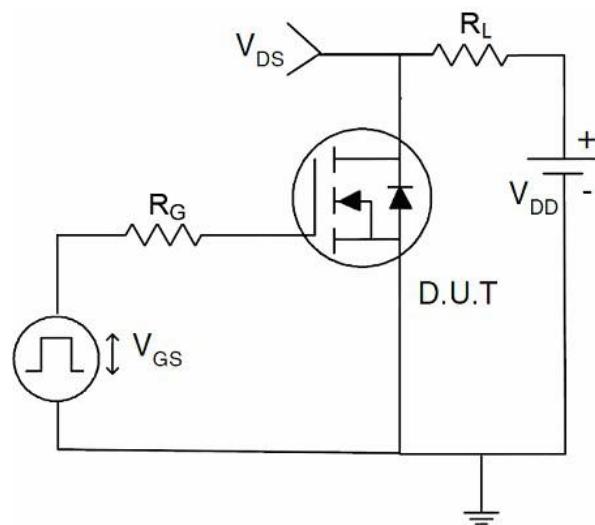
1 EAS Test Circuit



2 Gate Charge Test Circuit

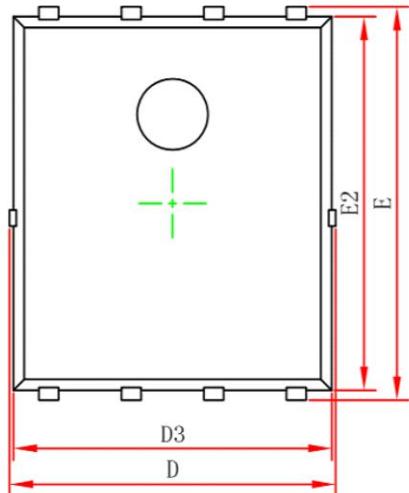


3 Switch Time Test Circuit

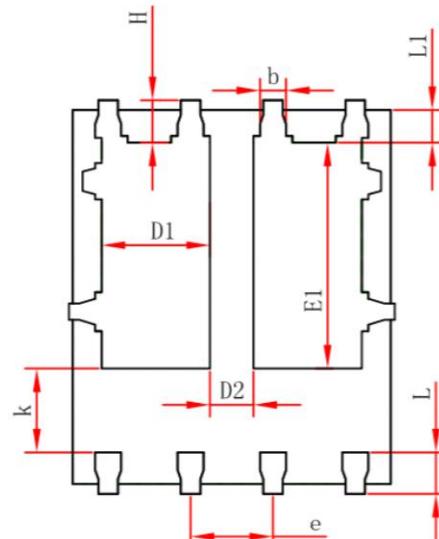


Package Information

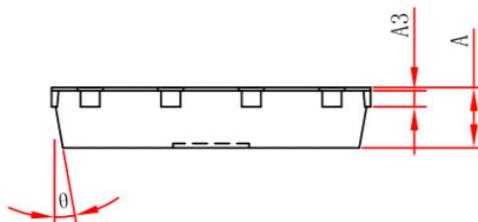
- PDFN5*6-8L-B



Top View



Bottom View



Side View

| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.900 | 1.000 | 0.035 | 0.039 |
| A3 | 0.154REF. | | 0.006REF. | |
| D | 4.944 | 5.096 | 0.195 | 0.201 |
| E | 5.974 | 6.126 | 0.235 | 0.241 |
| D1 | 1.470 | 1.870 | 0.058 | 0.074 |
| D2 | 0.470 | 0.870 | 0.019 | 0.034 |
| E1 | 3.375 | 3.575 | 0.133 | 0.141 |
| D3 | 4.824 | 4.976 | 0.190 | 0.196 |
| E2 | 5.674 | 5.826 | 0.223 | 0.229 |
| k | 1.190 | 1.390 | 0.047 | 0.055 |
| b | 0.350 | 0.450 | 0.014 | 0.018 |
| e | 1.270TYP. | | 0.050TYP. | |
| L | 0.559 | 0.711 | 0.022 | 0.028 |
| L1 | 0.424 | 0.576 | 0.017 | 0.023 |
| H | 0.574 | 0.726 | 0.023 | 0.029 |
| θ | 10° | 12° | 10° | 12° |